



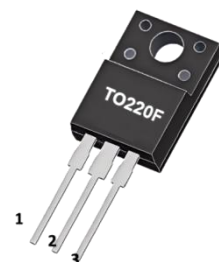
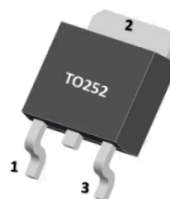
■ GENERAL DESCRIPTION

The BT152 is a thyristor, it uses our advanced technology to provide customers with high bidirectional blocking voltage capability and high thermal cycling performance, etc.

The BT152 is suitable for motor control, industrial, static switching, heating and domestic lighting, etc.

■ FEATURES

- * High bidirectional blocking voltage capability
- * High thermal cycling performance



Pin1:K (Cathode)
Pin2:A (Anode)
Pin3:G (Gate)

■ ABSOLUTE MAXIMUM RATINGS (TC=25 °C, unless otherwise specified)

SYMBOL	PARAMETER		TEST CONDITION	VALUE	UNIT
V _{DRM}	Repetitive Peak off-state voltage	BT152	T _J =25℃	800	V
I _{T(AV)}	Average On-State Current（half sine wave;T _c ≤103℃）			13	A
I _{T(RMS)}	RMS On-State Current（All Conduction Angles）			20	A
I _{TSM}	Non-repetitive peak on-state current (half sine wave;T _J =25℃ prior to surge)	t=10ms	200	A	
		t=8.3ms	220		
I ² t	I ² t for fusing	t=10ms	200	A ² S	
di/dt	Critical rate of rise of on-state current	I _{TM} = 50A; I _G =0.2A; dI _G /dt =0.2A/μs	200	A/μs	
I _{GM}	Peak gate current			5	A
V _{GM}	Peak gate voltage			5	V
V _{RGM}	Peak Reverse Gate Voltage			5	V
P _{GM}	Peak gate Power			20	W
P _{G(AV)}	Average gate Power Dissipation (over any 20ms period)	T _J =125℃		0.5	W
T _J	Operating Junction Temperature			125	℃
T _{stg}	Storage Temperature			-40 to +150	℃

Notes: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.



■ THERMAL RESISTANCES

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220F	R θ JA	60	K/W
	TO-252		75	
Junction to Case	TO-220F	R θ JC	1.1	K/W
	TO-252		2.3	

■ ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
Gate trigger current	I _{GT}	V _D =12V;I _T =0.1A		3	32	mA
Gate trigger voltage	I _L	V _D =12V;I _{GT} =0.1A		25	80	mA
Holding current	I _H	V _D =12V;I _{GT} =0.1A		15	60	mA
On-State Voltage	V _T	I _T =40A		1.4	1.75	V
Gate Trigger Voltage	V _{GT}	V _D =12V;I _T =0.1A		0.6	1.5	V
		V _D =V _{DRM(max)} ,I _T =0.1A,T _J =125°C	0.25	0.4		
Off-State Leakage Current	I _{DRM}	V _D =V _{DRM(max)} ,V _R =V _{RRM(max)} ,		0.2	1.0	mA
	I _{RRM}	T _J =125°C		0.2	1.0	
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of off-state Voltage	dV _D /dt	V _{DM} =67%V _{DRM(max)} , T _J =125°C, Exponential Waveform Gate Open Circuit	200	300		V/μs
Gate Controlled Turn-on Time	t _{gt}	V _D =V _{DRM(max)} , I _G =0.1A dI _G /dt=5A/μs, I _{TM} =40A		2		μs
Circuit Commutated Turn-Off Time	t _Q	I _{TM} =50A, V _R =25V, R _{GK} =100Ω dI _{TM} /dt=30A/μs, dV _D /dt=50V/μs		70		μs



■ TYPICAL CHARACTERISTICS (1)

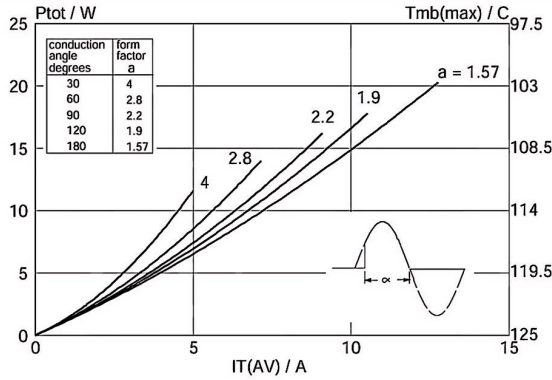


Fig.1. Maximum on-state dissipation, P_{tot} , versus average on-state current, $I_{T(AV)}$, where $a = \text{form factor} = I_{T(RMS)} / I_{T(AV)}$.

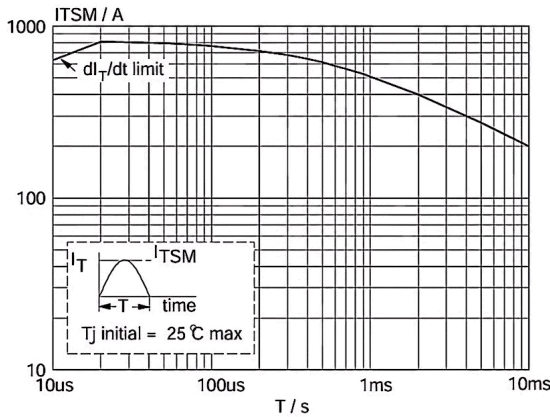


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 10\text{ms}$.

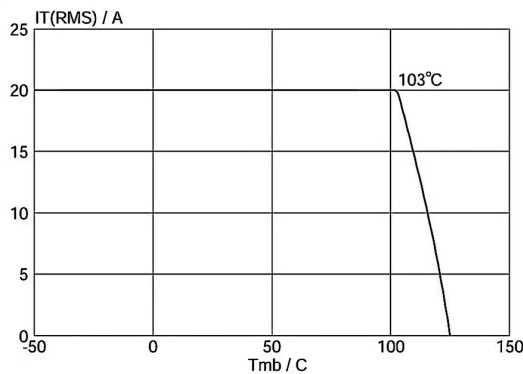


Fig.3. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

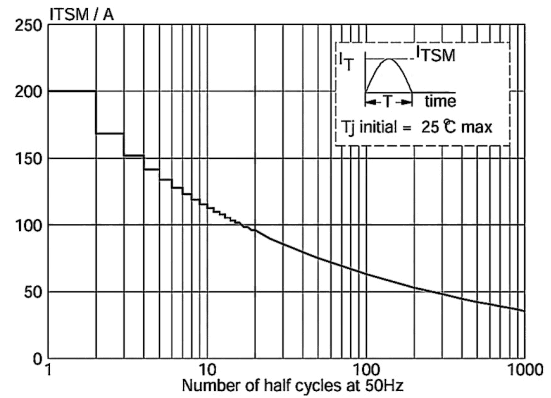


Fig.4. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50\text{ Hz}$.

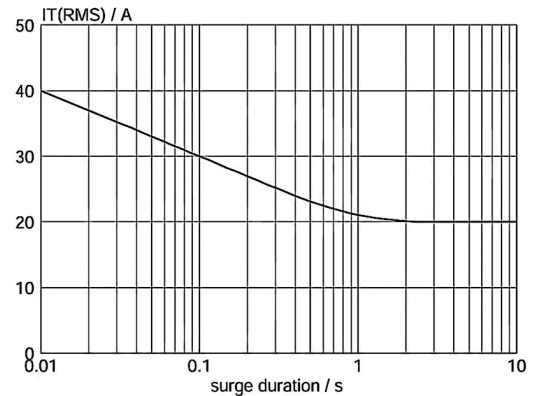


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50\text{ Hz}$; $T_{mb} \leq 103^\circ\text{C}$.

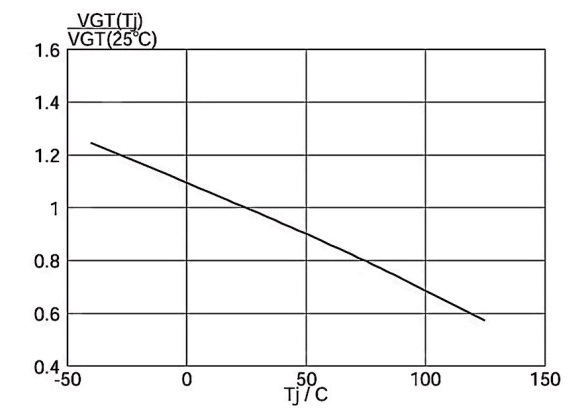


Fig.6. Normalised gate trigger voltage $V_{GT}(T_J) / V_{GT}(25^\circ\text{C})$, versus junction temperature T_J .



■ TYPICAL CHARACTERISTICS (2)

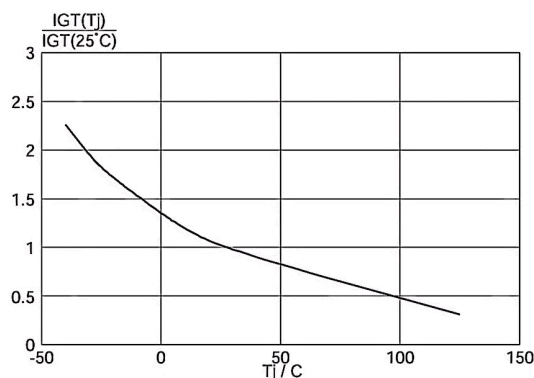


Fig. 7. Normalised gate trigger current $I_{GT}(T_J) / I_{GT}(25^\circ\text{C})$, versus junction temperature T_J .

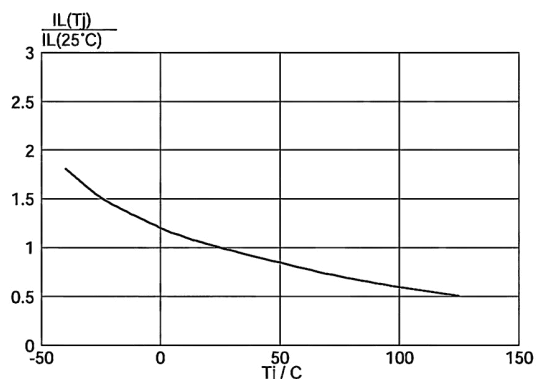


Fig. 8. Normalised latching current $I_L(T_J) / I_L(25^\circ\text{C})$, versus junction temperature T_J .

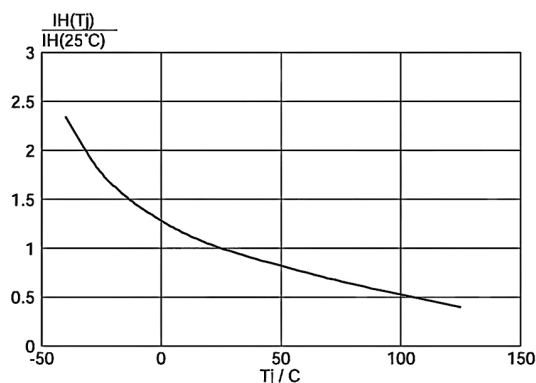


Fig. 9. Normalised holding current $I_H(T_J) / I_H(25^\circ\text{C})$, versus junction temperature T_J .

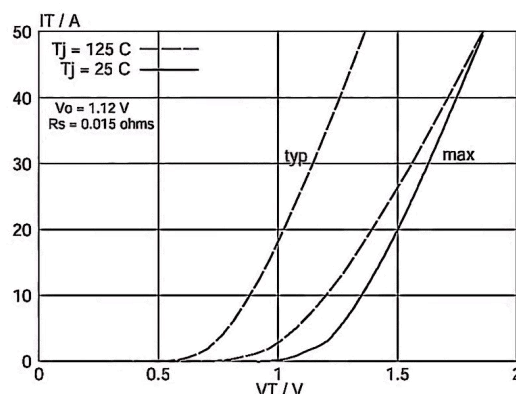


Fig. 10. Typical and maximum on-state characteristic.

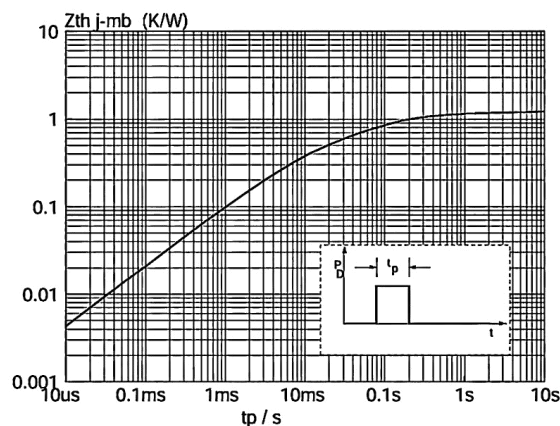


Fig. 11. Transient thermal impedance $Z_{th(j-mb)}$ versus pulse width t_p .

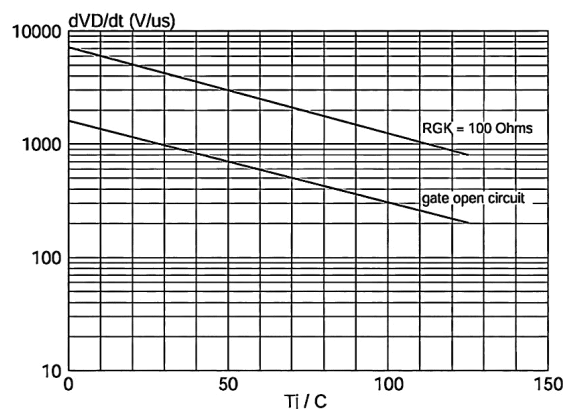
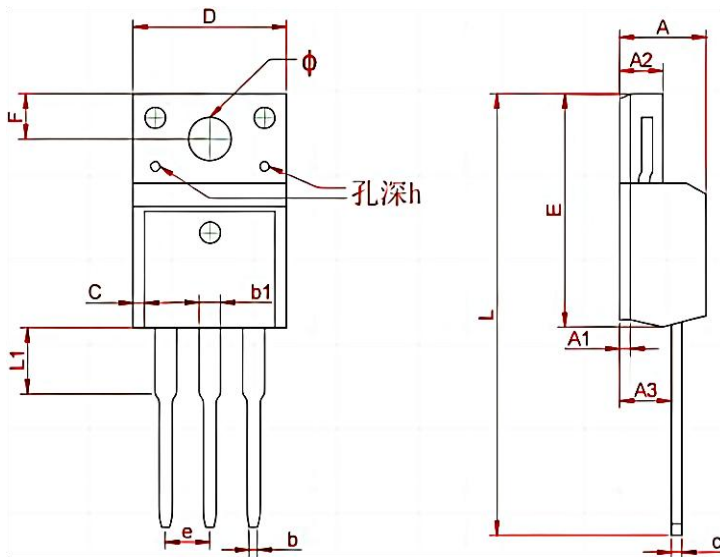


Fig. 12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature T_J .



■ **TO- 220F PACKAGE OUTLINE DIMENSIONS**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max	Min	Max
A	4.300	4.750	0.169	0.185
A1	1.830 REF		0.072 REF	
A2	2.300	2.850	0.090	0.112
A3	2.500	2.900	0.098	0.114
b	0.400	0.420	0.016	0.016
b1	1.220	1.280	0.048	0.050
C	0.690	0.720	0.027	0.028
c	0.490	0.510	0.019	0.020
D	9.960	10.200	0.392	0.400
E	15.000	15.950	0.588	0.625
e	2.574 TYP		0.101TYP	
F	3.470 REF		0.136 REF	
y	3.200 REF		0.125 REF	
h	0.000	0.300	0.000	0.012
L	28.780	28.900	1.128	1.133
L1	2.990	3.100	0.117	0.122



■ TO - 252 Package Outline Dimensions

